IN THE CLAIMS:

Claims 18-92 and 136 were previously cancelled. None of the claims have been amended herein. All of the pending claims are presented below for convenience of the Patent Office. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as previously amended.

1. (Previously presented) A contact for a semiconductor device component, comprising:

a core comprising a polymer and configured to protrude from the semiconductor device component in a generally transverse orientation relative to a plane of the semiconductor device component; and

a conductive coating on at least a portion of the core.

2. (Original) The contact of claim 1, wherein the core is flexible and resilient.

3. (Original) The contact of claim 1, wherein the core is substantially rigid.

4. (Previously presented) The contact of claim 1, wherein the core comprises a plurality of adjacent, mutually adhered regions of the polymer.

5. (Original) The contact of claim 1, wherein the polymer comprises a photoimagable polymer.

6. (Original) The contact of claim 1, wherein the core includes a base, an intermediate section, and a contact tip.

7. (Original) The contact of claim 6, wherein the intermediate section is flexible and resilient.

8. (Original) The contact of claim 6, wherein the base is configured to be secured to the semiconductor device component.

9. (Original) The contact of claim 6, wherein the conductive coating covers at least a portion of the contact tip and at least a portion of the intermediate section.

10. (Original) The contact of claim 9, wherein the conductive coating substantially covers the contact tip.

11. (Original) The contact of claim 9, wherein the contact tip is configured to electrically communicate with another contact of another semiconductor device component.

12. (Original) The contact of claim 9, wherein the conductive coating also covers at least a portion of the base.

13. (Original) The contact of claim 12, wherein a portion of the conductive coating on the base is configured to electrically communicate with a corresponding conductive element of the semiconductor device component.

14. (Original) The contact of claim 9, wherein the portion of the conductive coating on the intermediate section is configured to electrically communicate with a corresponding conductive element of the semiconductor device component.

15. (Original) The contact of claim 6, wherein the contact tip is enlarged relative to the intermediate section.

16. (Original) The contact of claim 1, wherein the conductive coating substantially covers the core.

17. (Original) The contact of claim 1, wherein the conductive coating comprises a plurality of layers of conductive material.

18.-92. (Cancelled)

93. (Previously presented) The contact of claim 1, wherein the core protrudes from a contact pad of the semiconductor device component.

94. (Previously presented) The contact of claim 1, wherein the core comprises a filament.

95. (Previously presented) A contact for a semiconductor device component, comprising:

a core comprising a filament comprising dielectric material and configured to protrude from the semiconductor device component in a generally transverse orientation relative to a plane of the semiconductor device component; and

a conductive coating on at least a portion of the core.

96. (Previously presented) The contact of claim 95, wherein the core is flexible and resilient.

97. (Previously presented) The contact of claim 95, wherein the core is substantially rigid.

98. (Previously presented) The contact of claim 95, wherein the core comprises a plurality of adjacent, mutually adhered regions comprising the dielectric material.

99. (Previously presented) The contact of claim 98, wherein the plurality of adjacent, mutually adhered regions comprises a plurality of at least partially superimposed, contiguous, mutually adhered layers.

100. (Previously presented) The contact of claim 95, wherein the dielectric material comprises a polymer.

101. (Previously presented) The contact of claim 100, wherein the polymer comprises a photoimagable polymer.

102. (Previously presented) The contact of claim 95, wherein the core includes a base, an intermediate section, and a contact tip.

103. (Previously presented) The contact of claim 102, wherein the intermediate section is flexible and resilient.

104. (Previously presented) The contact of claim 102, wherein the base is configured to be secured to the semiconductor device component.

105. (Previously presented) The contact of claim 102, wherein the conductive coating covers at least a portion of the contact tip and at least a portion of the intermediate section.

106. (Previously presented) The contact of claim 105, wherein the conductive coating substantially covers the contact tip.

107. (Previously presented) The contact of claim 106, wherein the contact tip is configured to electrically communicate with a contact of another semiconductor device component.

108. (Previously presented) The contact of claim 105, wherein the conductive coating also covers at least a portion of the base.

109. (Previously presented) The contact of claim 108, wherein a portion of the conductive coating on the base is configured to electrically communicate with a corresponding conductive element of the semiconductor device component.

110. (Previously presented) The contact of claim 105, wherein the portion of the conductive coating on the intermediate section is configured to electrically communicate with a corresponding conductive element of the semiconductor device component.

111. (Previously presented) The contact of claim 102, wherein the contact tip is enlarged relative to the intermediate section.

112. (Previously presented) The contact of claim 95, wherein the conductive coating substantially covers the core.

113. (Previously presented) The contact of claim 95, wherein the conductive coating comprises a plurality of contiguous regions of conductive material.

114. (Previously presented) The contact of claim 113, wherein the plurality of contiguous regions comprises a plurality of layers.

115. (Previously presented) The contact of claim 95, wherein the core is configured to protrude from a contact pad of the semiconductor device component.

116. (Previously presented) A contact for a semiconductor device component, comprising:

a core comprising a dielectric material configured to be secured to and protrude from a contact pad of the semiconductor device component; and

a conductive coating on at least a portion of the core.

117. (Previously presented) The contact of claim 116, wherein the core is flexible and resilient.

118. (Previously presented) The contact of claim 116, wherein the core is substantially rigid.

119. (Previously presented) The contact of claim 116, wherein the core comprises a plurality of adjacent, mutually adhered regions comprising the dielectric material.

120. (Previously presented) The contact of claim 119, wherein the plurality of adjacent, mutually adhered regions comprises a plurality of at least partially superimposed, contiguous, mutually adhered layers.

121. (Previously presented) The contact of claim 116, wherein the dielectric material comprises a polymer.

122. (Previously presented) The contact of claim 121, wherein the polymer comprises a photoimagable polymer.

123. (Previously presented) The contact of claim 116, wherein the core includes a base, an intermediate section, and a contact tip.

124. (Previously presented) The contact of claim 123, wherein the intermediate section is flexible and resilient.

125. (Previously presented) The contact of claim 123, wherein the base is configured to be secured to the semiconductor device component.

126. (Previously presented) The contact of claim 123, wherein the conductive coating covers at least a portion of the contact tip and at least a portion of the intermediate section.

127. (Previously presented) The contact of claim 126, wherein the conductive coating substantially covers the contact tip.

128. (Previously presented) The contact of claim 127, wherein the contact tip is configured to electrically communicate with a contact of another semiconductor device component.

129. (Previously presented) The contact of claim 126, wherein the conductive coating also covers at least a portion of the base.

130. (Previously presented) The contact of claim 129, wherein a portion of the conductive coating on the base is configured to electrically communicate with a corresponding conductive element of the semiconductor device component.

131. (Previously presented) The contact of claim 126, wherein the portion of the conductive coating on the intermediate section is configured to electrically communicate with a corresponding conductive element of the semiconductor device component.

132. (Previously presented) The contact of claim 123, wherein the contact tip is enlarged relative to the intermediate section.

133. (Previously presented) The contact of claim 116, wherein the conductive coating substantially covers the core.

134. (Previously presented) The contact of claim 116, wherein the conductive coating comprises a plurality of contiguous regions of conductive material.

135. (Previously presented) The contact of claim 134, wherein the plurality of contiguous regions comprises a plurality of layers.

136. (Cancelled)